SPECIFICATION FOR APPROVAL

REF. :

PROD. NAME	Shielded SMD Power Inductor	ABC'S DWG NO.	SS1307□□□□L□-□□□		
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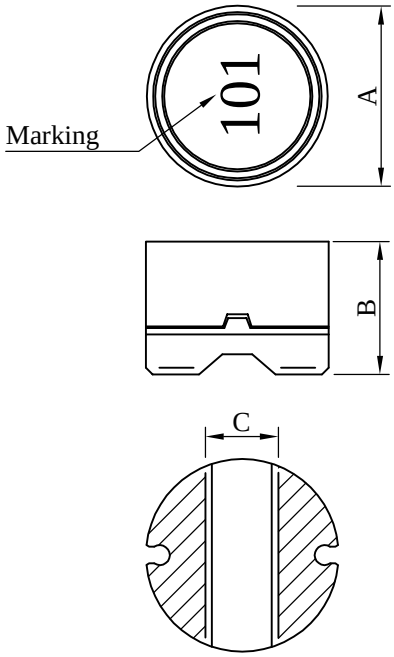
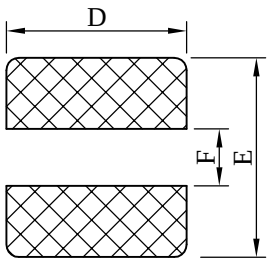
Ⅰ．Configuration and dimensions：





(PCB Pattern)

Unit：m/m

A	B	C	D	E	F
13.00 ±0.3	7.00 ±0.3	5.00 typ.	14.00 ref.	14.00 ref.	4.50 ref.

Ⅱ．Description：

a．Ferrite drum core construction.

b．Magnetically shielded.

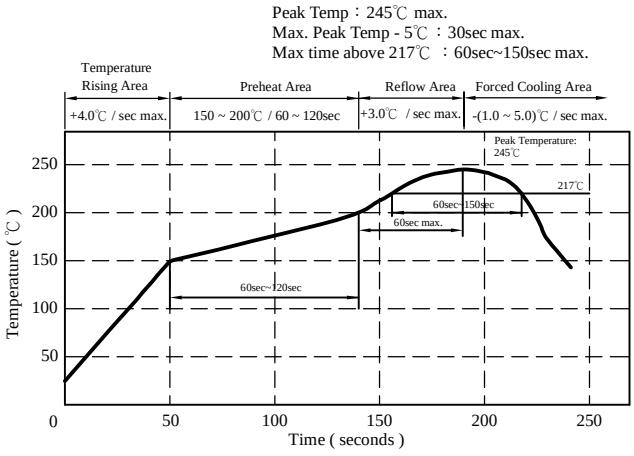
c．Enamelled copper wire：F class

d．Product weight： 3.30 g（ref.）

e．Moisture sensitivity Level 1

f．Products comply with RoHS' requirements

g．Halogen free available



Ⅲ．General specification：

a．Storage temp.：-40℃ ----+125℃

b．Operating temp.：-40℃----+125℃

(Temp. rise included)

c．Resistance to solder heat：245℃.10 secs.

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Ⅳ．Electrical characteristics：

DWG No.	Inductance (μH)	Q ref.	Test Freq. (Hz)	SRF (MHz) nom.	RDC (Ω) max.	Irms (A) typ.	Isat (A) typ.
SS1307100ML□-□□□	10 ±20%	46	2.520M	15.0	0.04	4.60	6.50
SS1307150ML□-□□□	15 ±20%	45	2.520M	14.0	0.05	4.00	5.60
SS1307220ML□-□□□	22 ±20%	42	2.520M	13.0	0.06	3.50	4.50
SS1307330ML□-□□□	33 ±20%	50	2.520M	12.0	0.08	2.80	3.70
SS1307470ML□-□□□	47 ±20%	50	2.520M	10.0	0.12	2.40	3.20
SS1307680ML□-□□□	68 ±20%	48	2.520M	8.0	0.16	2.00	2.70
SS1307101ML□-□□□	100 ±20%	48	0.796M	6.0	0.21	1.60	2.00
SS1307151ML□-□□□	150 ±20%	42	0.796M	5.0	0.30	1.30	1.70
SS1307221ML□-□□□	220 ±20%	38	0.796M	4.0	0.50	1.10	1.50
SS1307331ML□-□□□	330 ±20%	38	0.796M	3.0	0.75	0.80	1.20
SS1307471ML□-□□□	470 ±20%	36	0.796M	2.5	1.10	0.72	0.95
SS1307681ML□-□□□	680 ±20%	36	0.796M	2.0	1.45	0.60	0.85
SS1307102ML□-□□□	1000 ±20%	32	0.252M	1.5	2.10	0.50	0.70

1). □：Packaging information：□ Code

2). "-□□□"：Reference code

3). Electrical specifications at 25℃

4). Inductance Test Freq.：100kHz / 0.1V

5). Irms base on Temp. rise 40℃ typ.

6). Isat base on △L/L0A=10% typ.

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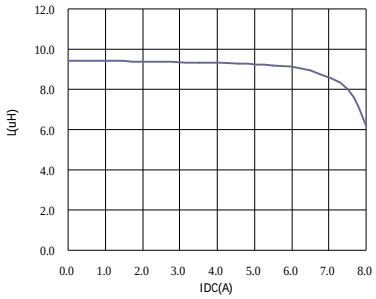
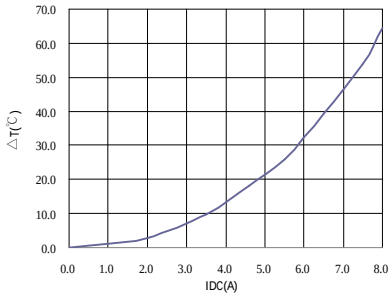
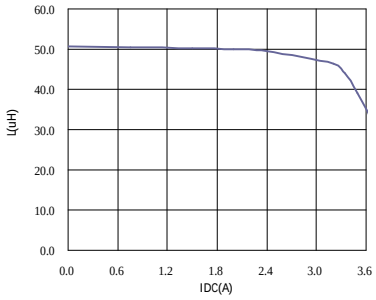
V ． Curve：

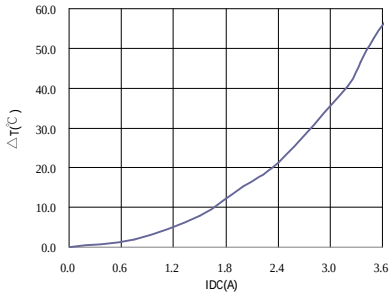
SS1307100ML□



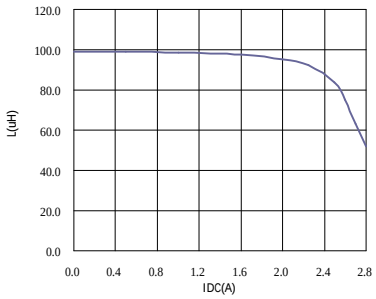


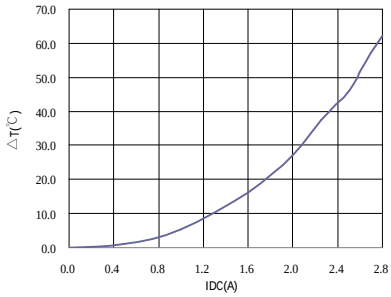
SS1307470ML□



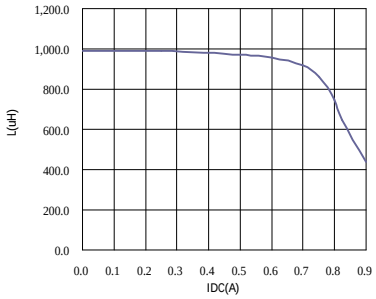


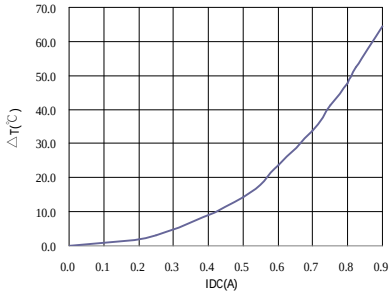
SS1307101ML□





SS1307102ML□





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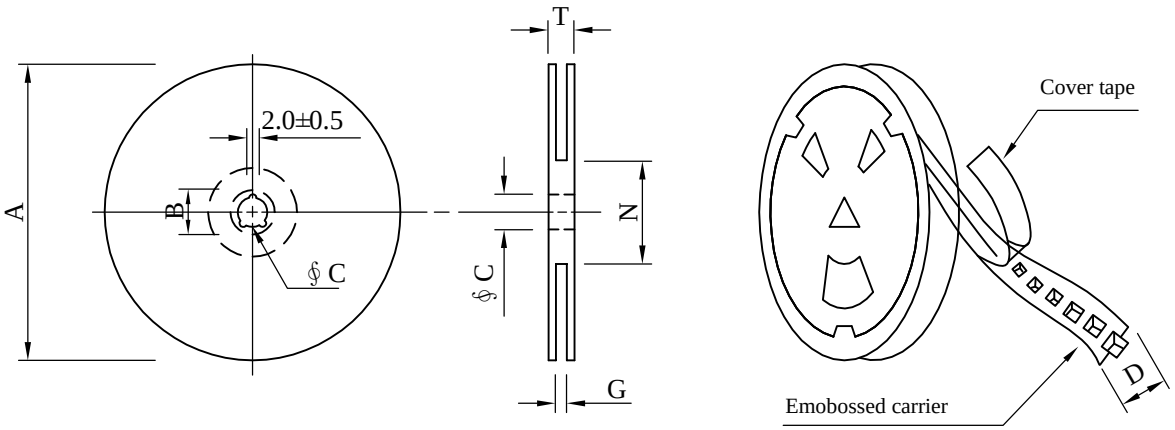
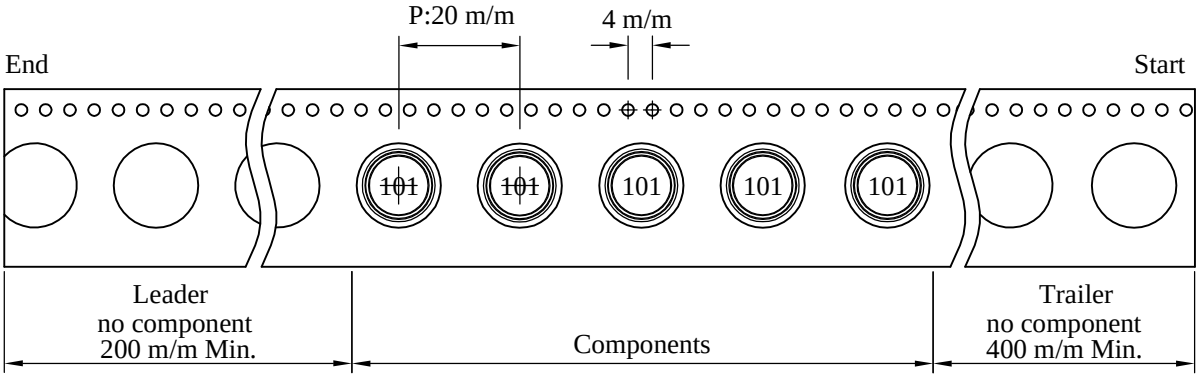
Ⅵ．Packaging information：

(1) Configuration



※Carrier tape width : D



User direction of feed

(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
13 - 24	330	21±0.8	13±0.5	24	26^{+0}	60^{-0}	30.4

(3) Q'TY & G.W. Per package

Code	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
B	400	1810	13 - 24	1,600	8.5	38 x 37 x 22

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Ⅶ．Reliability test：

Item	Reference documents	Test Condition	Test Specification
1.High Temperature Exposure	MIL-STD-202 Method 108	1.Temperature: 125±2℃ 2.Time:96±2 hours.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
2.Temperature Cycling	JESD22-A 104	1.Temperature: -40℃ ~ +125℃ 2.Number of cycle:100 cycle 3.Dwell time:30 minutes	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
3.Biased Humidity Test	MIL-STD-202 Method 103	1.Temperature：85±2 ℃ 2.Humidity: 85% RH. 3.Time:96±2 Hours	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
4.Operational Life	JESD22-A 108	1.Temperature: 125℃ (Temp. rise included) 2.Time:96±2 hours. 3.Rated current	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
5.External Visual	JESD22-B 101 & MIL-STD-883 Method 2009	Inspect product constructions, marking and workmanship.	1.No pollution on the surface of products. 2.Clear marking. 3.No crack.
6.Physical Dimensions	JESD22-B 100	Verify physical dimensions to the applicable product detail specification.	Per product specification standard
7.Resistance to solvents	MIL-STD-202 Method 215	Immerse into solvent for 3±0.5 minutes & brush 10 times for 3 cycles.	1.No body change in apperarance. 2.No marking blurred. 3.Inductance shall not change more than ±20%.
8.Vibration Test	MIL-STD-202 Method 204	1.Frequency and Amplitued : 10-2000-10 Hz, 1.5 mm. 2.Direction:X, Y, Z 3.Test duration:2 hours for each direction, 6 hours in total.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
9.Resistance To Soldering Heat Test	MIL-STD-202 Method 210 & J-STD020D.1	1.Highest temperature：245±5℃. 2.Time（temp.≧ 217℃）：60~150 Second. 3.IR reflow times：3 times.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
10.Saturation Current	JIS C 6436 & User SPEC.	1.Applied rated current for 5 second. 2.Saturation current	Inductance shall not drop more than 10% typ.
11.Over load	JIS C 6436 & User SPEC.	1.Applied one and half rated current for a period of 5 minutes. 2.Rated current	No electrical or mechanical damage
12.Temperature Rise Current	JIS C 6436 & User SPEC.	1.Applied rated current for 10 minutes. 2.Temperature measure by digital surface thermometer. 3.Irms current	Surface temperature rise is less than 40℃ typ.
13.Solderability Test	J-STD-002 & JESD22-B 102	1.Baking in pre-testing：150±5℃ / 16Hours±30 min. 2.Peak temperature：240±5℃ 3.Time（temp.≧217℃）：60~150 second. 4.IR reflow times：1 times.	More than 95% soldering coverage min on terminations.
14.Electrical Characteriazation	MIL-STD-202 Method 304 & User SPEC.	1.Operating temperature：-40℃~125℃ 2.Room temperature：25℃.	1.No mechanical or electrical damage. 2.Inductance shall not change more than ±20%.
15.Drop	CNS-C6354 & GB/T 2423.8	1.Products shall be mounted on SPEC. PCB and dropped down from a height of 1m 2.Drop total time：6 time (Every side of sample drop 2 time)	1. Adhesion on PCB shall be enough. 2. Product appearance shall not break. 3. No electrical damage.
16.Terminal Strength Test	IEC 60068-2-21	1.Apply push force to samples mounted on PCB. 2.Force of 1.8 kg for 60±1 seconds.	After test, inductors shall be no mechanical damage.